

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc2636hde-hz8#trpbf

(Engineering Calculation)

DFN 4mm X 3mm Exposed Pad

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**TOTAL MASS (g) : 0.03174**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001752	1000000	55198.8867188		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.013123	975000	413456.03125		
		Iron (Fe)	7439-89-6	0.000323	24000	10176.5068359		
		Phosphorus (P)	7723-14-0	0.000004	300	126.024856567		
		Zinc (Zn)	7440-66-6	0.000009	700	283.555908203		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.013459</b>	<b>1000000</b>	<b>424042.09375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000626	1000000	19715.6035156		
		<b>External Plating Total:</b>				<b>0.000626</b>	<b>1000000</b>	<b>19715.6035156</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000302	1000000	9514.87695312		
<b>Internal Plating Total:</b>				<b>0.000302</b>	<b>1000000</b>	<b>9514.87695312</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000836	750000	26339.1953125		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000279	250000	8790.23339844		
<b>Die Attach Total:</b>				<b>0.001115</b>	<b>1000000</b>	<b>35129.4296875</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001876	130000	59105.6523438		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.012410	860000	390992.09375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000144	10000	4536.89453125		
		<b>Encapsulation Total:</b>				<b>0.014430</b>	<b>1000000</b>	<b>454634.65625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000056	1000000	1764.34802246		
					<b>TOTAL MASS (g) :</b>	<b>0.03174</b>		